

Tool ID: 205  
Tool Location: 107

Equipment Information Sheet  
**PT740 Etcher**

**Manager:** Mac McMurdy  
**Backup:** Jeremy Clark

607-254-4813  
607-254-6487

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

**SAFETY**

- No unusual hazards during normal operation
- Cl2, BCl3, CH4 gases used

**USAGE RESTRICTIONS**

- No buddy system restrictions imposed on normal operation
- User must remain in lab during operation

**SCHEDULING/SIGN-UP RESTRICTIONS**

- None

Minimum Tool Time: 15 minutes

**MATERIALS COMPATIBILITY CATEGORY**

Tool Category 5: Class A and B Metals and Compounds	
Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

**High Vapor Pressure Metals and Compounds**are materials that have a vapor pressure above 1e-6 Torr at 400 C.

**Additional Material Restrictions and Exceptions**

- Use sapphire carrier wafer for pieces

Last Updated: 10/27/2022